



MULTI-INNO TECHNOLOGY CO., LTD.

www.multi-inno.com

LCD MODULE SPECIFICATION

Model : MI0700S1T-3

This module uses ROHS material

For Customer's Acceptance:

Customer	
Approved	
Comment	

This specification may change without prior notice in order to improve performance or quality. Please contact Multi-Inno for updated specification and product status before design for this product or release of this order.

Revision	1.0
Engineering	
Date	2013-05-29
Our Reference	

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■ GENERAL INFORMATION

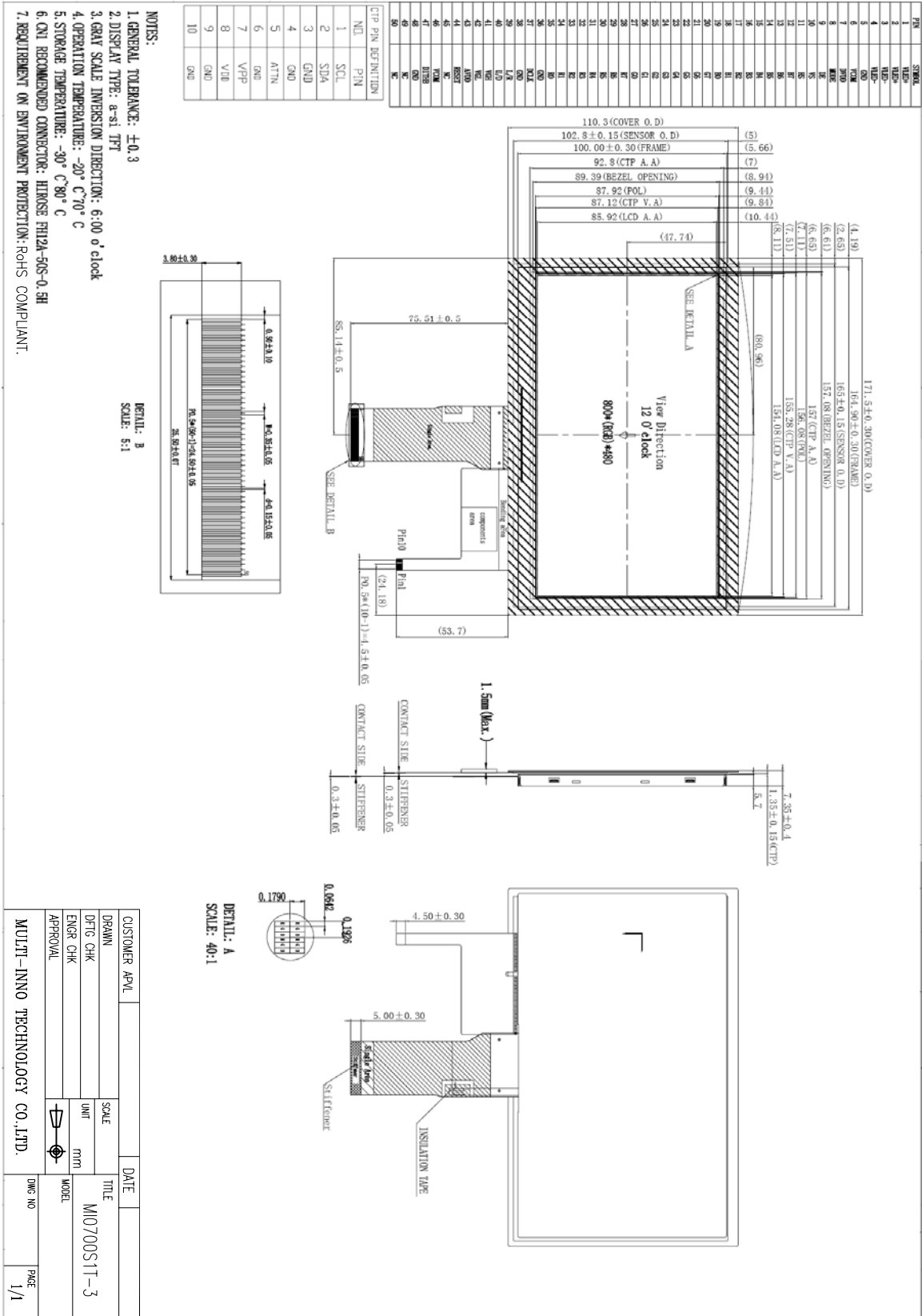
Item	Contents	Unit
LCD type	TFT/Transmissive/Normally white	/
Size	7.0	Inch
Viewing direction	12:00	O' Clock
Gray scale inversion direction	6:00	O' Clock
LCM (W × H) × D	164.90×100.00×7.35	mm ³
LCD active area (W×H)	154.08 × 85.92	mm ²
CTP active area (W × H)	155.24×87.12	mm ²
Pixel pitch (W×H)	0.1926×0.179	mm ²
Number of dots	800 (RGB) × 480	/
CTP controller	NT11003	/
Backlight type	24 LEDs	/
TFT LCD interface type	RGB 24 bits	/
CTP interface type	I2C	/
Color depth	16.7M	/
Pixel configuration	R.G.B vertical stripe	/
LCD surface treatment	Anti-glare(3H)	/
CTP touch method	Bare finger	/
CTP structure	Glass lens-Glass sensor	/
Number of simultaneous touches	2 points	/
Minimum touch area	Φ6	mm
Finger touch pitch	13	mm
Input voltage	3.3	V
With/Without TSP	With CTP	/
Weight	TBD	g

Note 1: Viewing direction for best image quality is different from TFT definition, there is a 180 degree shift.

Note 2 : RoHS compliant;

Note 3: LCM weight tolerance: ± 5% .

EXTERNAL DIMENSIONS



■ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Min	Max	Unit
Power voltage	VDD	-0.5	5.0	V
	AVDD	-0.5	15.0	V
	VGH	-0.3	42.0	V
	VGL	-20.0	0.3	V
	VGH-VGL	-0.3	40.0	V
Backlight forward current	ILED	-	200	mA
Operating temperature	T _{OP}	-20	70	°C
Storage temperature	T _{ST}	-30	80	°C
Humidity	RH	-	90%(Max60°C)	RH

Note1: The parameter is for driver IC (gate driver, source driver) only

Note2: 80°C is the surface temperature of module

■ELECTRICAL CHARACTERISTICS

DC CHARACTERISTICS OF LCM

Parameter	Symbol	Min	Typ	Max	Unit
Voltage for logic circuit	VCC	3.0	3.3	3.6	V
Analog supply voltage	AVDD	9.88	10.4	10.92	V
Gate on voltage	VGG	14.4	16.0	17.6	V
Gate off voltage	VEE	-7.7	-7.0	-6.3	V
Common electrode driving signal	VCOM	3.68	3.7	3.72	V
Input voltage 'H' level	V _{IH}	0.7VCC	-	VCC	V
Input voltage 'L' level	V _{IL}	0	-	0.3VDD	V

Note1: For different LCM, the value may have a bit of difference.

Note2: To test the current dissipation, use "all Black Pattern".

DC CHARACTERISTICS OF CTP

Parameter	Min	Typ	Max	Unit	Note
power supply voltage	2.7	3.3	3.6	V	DC(noise should be under 100mV)
Power supply current	-	-	10	mA	

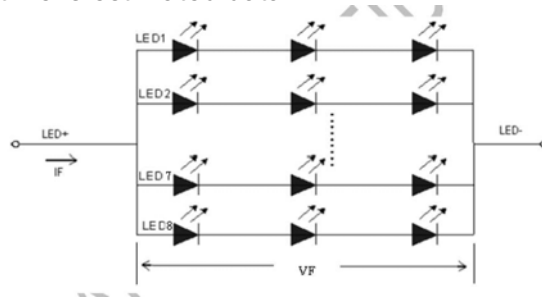
■ BACKLIGHT CHARACTERISTICS

Item	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward voltage	V _f	-	9.6	10.8	V	Note 1
Forward current	I _f	-	160	200	mA	
Backlight power consumption	W _{BL}	-	1536	2160	mW	
Life time	-	10000	-	-	Hrs	Note 3

Note 1: I_f is defined for one channel LED. There are total three LED channels in back light unit. Under LCM operating, the stable forward current should be inputted.

Note 2: Optical performance should be evaluated at $T_a=25^\circ\text{C}$ only.

Note 3: If LED is driven by high current, high ambient temperature & humidity condition. The life time of LED will be reduced. Operating life means brightness goes down to 50% initial brightness. Typical operating life time is estimated data.



■ELECTRO-OPTICAL CHARACTERISTICS

Item	Symbol	Condition	Min	Typ	Max	Unit	Remark	Note
Response time	Tr+Tf	$\theta=0^\circ$ $\varnothing=0^\circ$ $T_a=25^\circ\text{C}$	-	40	60	ms	FIG 1.	4
Contrast ratio	Cr		400	500	-	---	FIG 2.	1
Luminance uniformity	δ WHITE		-	75	-	%	FIG 2.	3
Surface Luminance	Lv		240	300	-	cd/m ²	FIG 2.	2
Viewing angle range	θ	$\varnothing = 90^\circ$	55	60	-	deg	FIG 3.	6
		$\varnothing = 270^\circ$	65	70	-	deg	FIG 3.	
		$\varnothing = 0^\circ$	65	70	-	deg	FIG 3.	
		$\varnothing = 180^\circ$	65	70	-	deg	FIG 3.	
CIE (x, y) chromaticity	Red	x	0.541	0.591	0.641	FIG 2.	5	
		y	0.300	0.350	0.390			
	Green	x	0.298	0.348	0.388			
		y	0.521	0.571	0.621			
	Blue	x	0.101	0.151	0.211			
		y	0.051	0.101	0.151			
	White	x	0.265	0.315	0.365			
		y	0.280	0.330	0.380			
NTSC	-	-	-	50	-	%	-	-
Reflectivity	-	-	-	-	4	%	-	8
HAZE	-	-	-	-	2	%	-	8

Note 1. Contrast Ratio(CR) is defined mathematically as For more information see FIG 2.

$$\text{Contrast Ratio} = \frac{\text{Average Surface Luminance with all white pixels (P1, P2, P3, P4, P5)}}{\text{Average Surface Luminance with all black pixels (P1, P2, P3, P4, P5)}}$$

Note 2. Surface luminance is the LCD surface from the surface with all pixels displaying white. For more information see FIG 2.

$$L_v = \text{Average Surface Luminance with all white pixels (P1, P2, P3, P4, P5)}$$

Note 3. The uniformity in surface luminance, δ WHITE is determined by measuring luminance at each test position 1 through 5, and then dividing the maximum luminance of 5 points luminance by minimum luminance of 5 points luminance. For more information see FIG 2.

$$\delta \text{ WHITE} = \frac{\text{Minimum Surface Luminance with all white pixels (P1, P2, P3, P4, P5)}}{\text{Maximum Surface Luminance with all white pixels (P1, P2, P3, P4, P5)}}$$

Note 4. Response time is the time required for the display to transition from White to black(Rise Time, Tr) and from black to white(Decay Time, Tf). For additional information see FIG 1. The test equipment is Autronic-Melchers's ConoScope. Series.

Note 5. CIE (x, y) chromaticity, The x, y value is determined by measuring luminance at each test position 1 through 5, and then make average value.

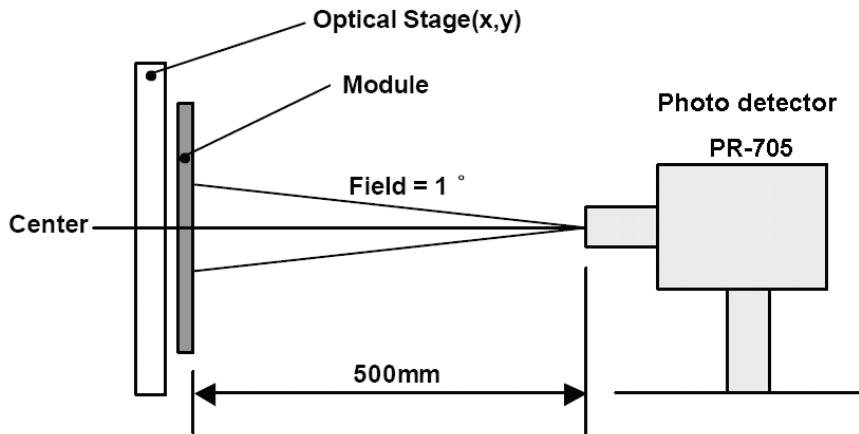
Note 6. Viewing angle is the angle at which the contrast ratio is greater than 2. For TFT module the contrast ratio is greater than 10. The angles are determined for the horizontal or x axis and the vertical or y axis with respect to the z axis which is normal to the LCD surface. For more information see FIG 3.

Note 7. For viewing angle and response time testing, the testing data is base on Autronic-Melchers's ConoScope. Series Instruments For contrast ratio, Surface Luminance, Luminance uniformity, CIE The test data is base on TOPCON's BM-5 photo detector.

Note8: Measuring equipments: DMS-501, PR-705. @550nm

Measuring condition:

- After stabilizing and leaving the panel alone at a given temperature for 30 min, the measurement should be executed,
- Measuring surroundings: a stable, windless and dark room,
- Measuring temperature: $T_a=25^{\circ}\text{C}$,
- 30 min after lighting the back-light.



Note2: conform to National standard GB2410—80 /ASTM D1003—61(1997)

FIG. 1 The definition of Response Time

The response time is defined as the following figure and shall be measured by switching the input signal for “black” and “white”.

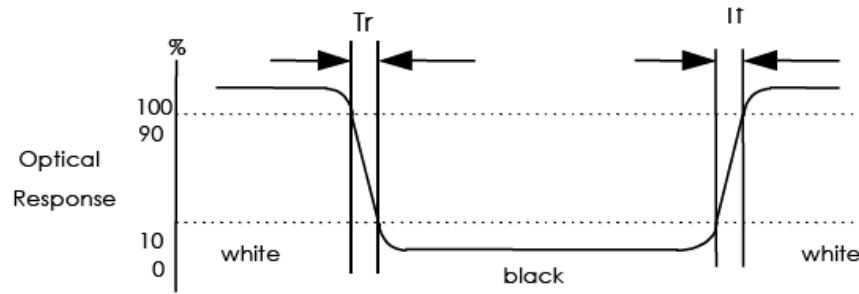


FIG. 2 Measuring method for Contrast ratio, surface luminance, Luminance uniformity , CIE (x, y) chromaticity

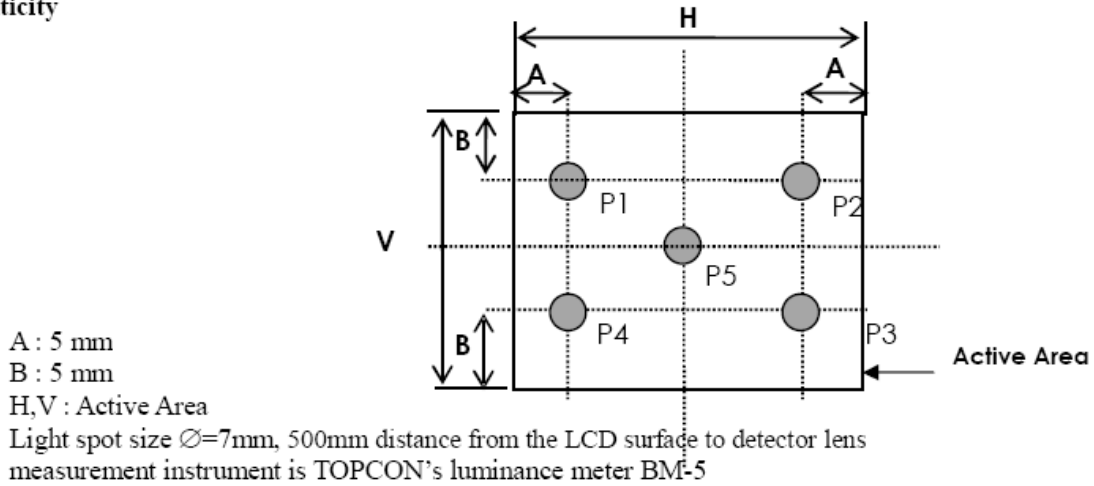
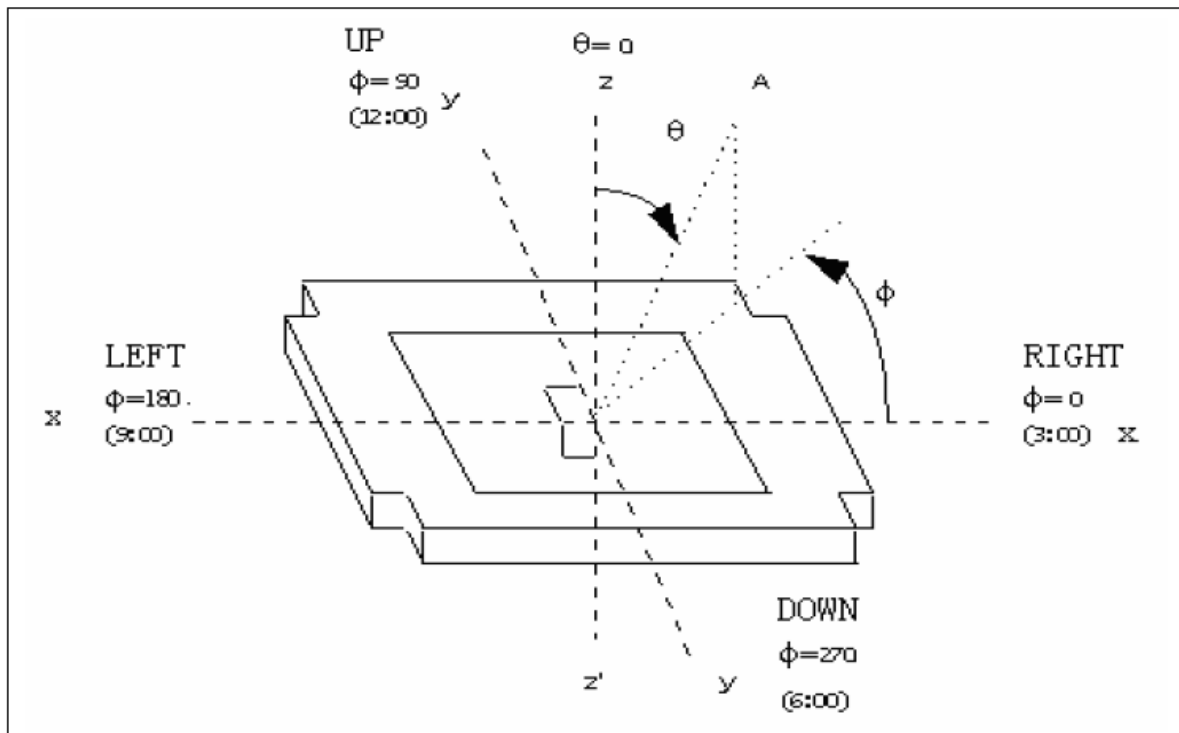


FIG. 3 The definition of viewing angle



■ INTERFACE DESCRIPTION

1. THE FPC CONNECTION OF LCM

PIN	Symbol	I/O	Description	Remark
1	VLED+	P	Led anode	
2	VLED+	P	Led anode	
3	VLED-	P	Led cathode	
4	VLED-	P	Led cathode	
5	GND	P	Ground	
6	VCOM	P	Common voltage input	
7	VCC	P	Digital power supply	
8	MODE	I	DE/SYNC mode select. H:DE mode, L:SYNC mode	
9	DE	I	Data enable signal, active high to enable data	
10	VSYNC	I	Vertical sync input, negative polarity	
11	HSYNC	I	Horizontal sync input, negative polarity	
12	B7	I	Blue data (MSB)	
13	B6	I	Blue data	
14	B5	I	Blue data	
15	B4	I	Blue data	
16	B3	I	Blue data	
17	B2	I	Blue data	
18	B1	I	Blue data	
19	B0	I	Blue data (LSB)	
20	G7	I	Green data (MSB)	
21	G6	I	Green data	
22	G5	I	Green data	
23	G4	I	Green data	
24	G3	I	Green data	
25	G2	I	Green data	
26	G1	I	Green data	
27	G0	I	Green data (LSB)	
28	R7	I	Red data (MSB)	
29	R6	I	Red data	
30	R5	I	Red data	
31	R4	I	Red data	
32	R3	I	Red data	
33	R2	I	Red data	
34	R1	I	Red data	
35	R0	I	Red data (LSB)	
36	GND	P	Ground	
37	DCLK	I	Clock for input data	
38	GND	P	Ground	
39	LR	I	Source left or right sequence control	
40	UD	I	Gate up or down scan control	



41	VGH	P	Positive power of TFT	
42	VGL	P	Negative power of TFT	
43	AVDD	P	Analog power supply	
44	RESET	I	Global reset pin	
45	NC	NC		
46	VCOM	P	Common voltage input	
47	DITHB	I	Dithering setting. H: 6bit resolution, L: 8bit resolution	
48	GND	P	Ground	
49	NC	NC		
50	NC	NC		

Note 1: I/O definition

I---Input, O---Output, P--- Power/Ground,N-No connection

Note 2: I/O definition

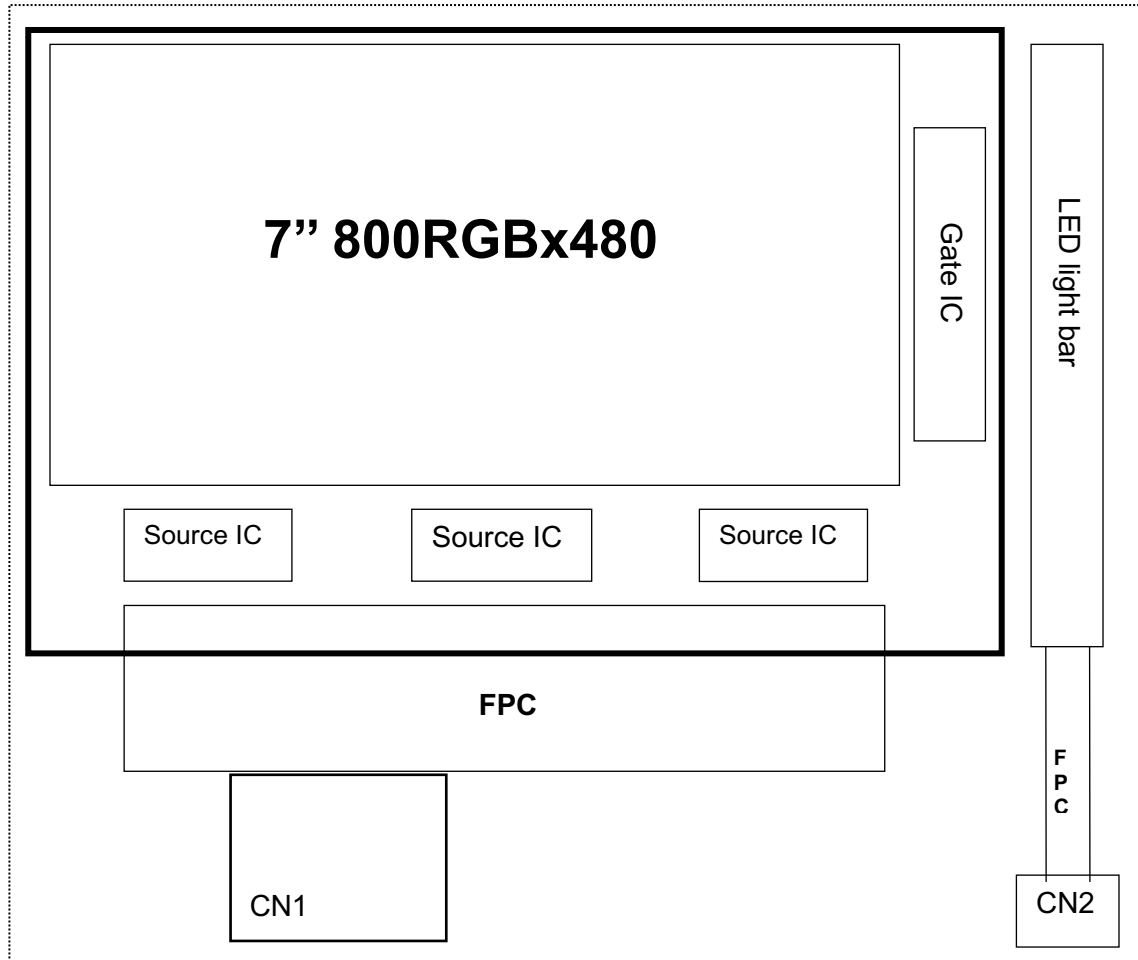
Scan control input		Scanning direction
UD	LR	
GND	VCC	Up to down, left to right
VCC	GND	Down to up, right to left
GND	GND	Up to down, right to left
VCC	VCC	Down to up, left to right

2. THE FPC CONNECTION OF CTP

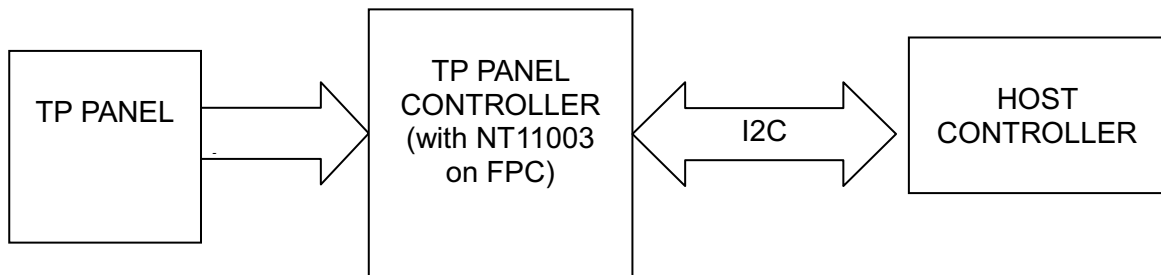
Pin No.	Symbol	I/O	Description	Remark
1	SCL	I	I2C clock input	
2	SDA	I/O	I2C data input and output	
3	GND	P	Groud	
4	GND	P	Groud	
5	ATTN	I/O	External interrupt to the host	
6	GND	P	Groud	
7	VPP	I/O	External interrupt from the host	
8	VDD	P	CTP power supply	
9	GND	P	Groud	
10	GND	P	Groud	

■ BLOCK DIAGRAM

1. TFT Block Diagram



2. CTP Circuit Block Diagram



■ APPLICATION NOTES

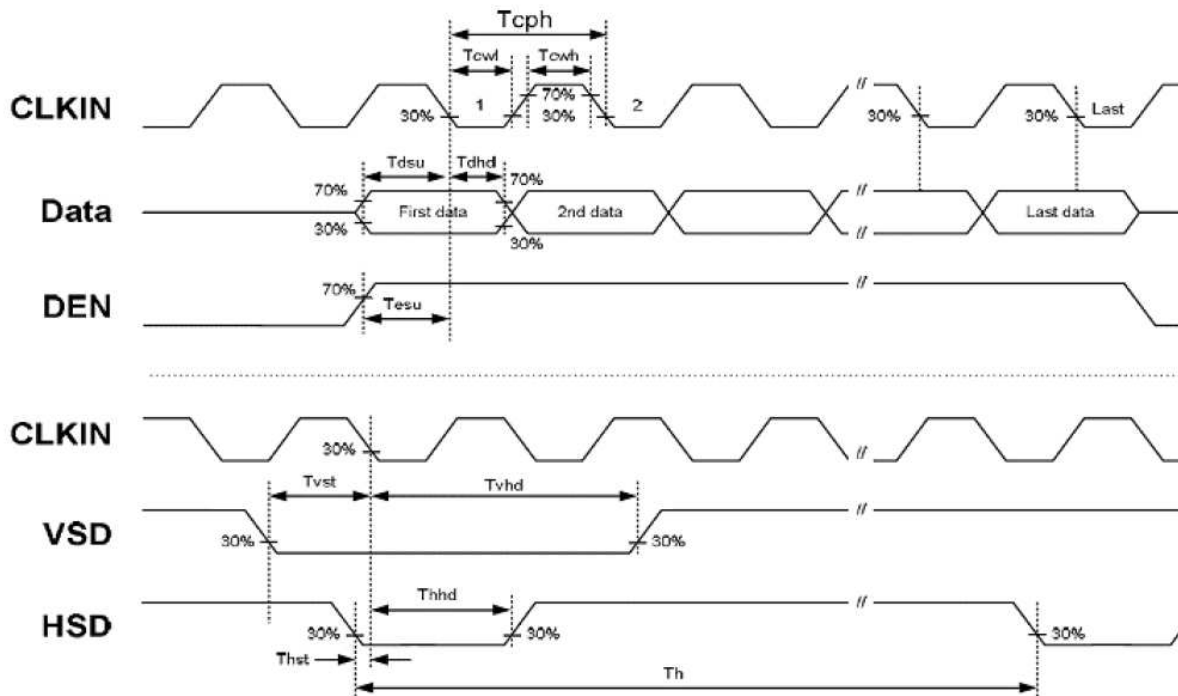
1 TIMING CHARACTERISTICS

1.1 TFT-LCD Input Timing

VCC=3.3V, GND=0V, Ta=25°C

Parameter	Symbol	Min	Typ	Max	Unit	Remark
DCLK frequency	F_{clk}	28	30.0	40.0	MHz	
DCLK cycle time	T_{cph}	25	33.3	36	ns	
DCLK pulse width	T_{cw}	40%	50%	60%	T_{cph}	
VS setup time	T_{vst}	8			ns	
VS hold time	T_{vhd}	8	-	-	ns	
HS setup time	T_{hst}	8			ns	
HS hold time	T_{hhd}	8	-	-	ns	
Data setup time	T_{dsu}	8			ns	Data to DCLK
Data hold time	T_{dhhd}	8	-	-	ns	Data to DCLK
DE setup time	T_{esu}	8	-	-	ns	
DE hold time	T_{ehd}	8	-	-	ns	

Input Clock and Data timing Diagram:



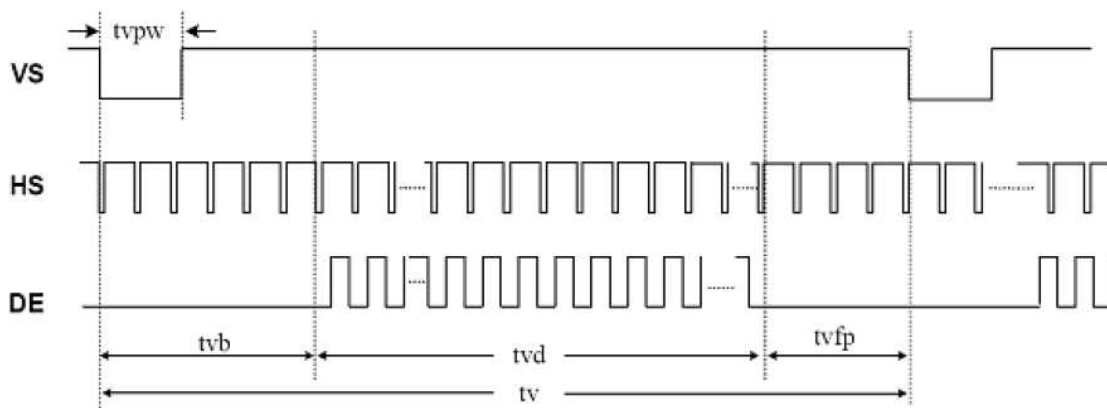
1.2 Recommended Timing Setting Of TCON

TCON (Embedded In Source IC) Input Timing (DCLK, HS, VS, DE)

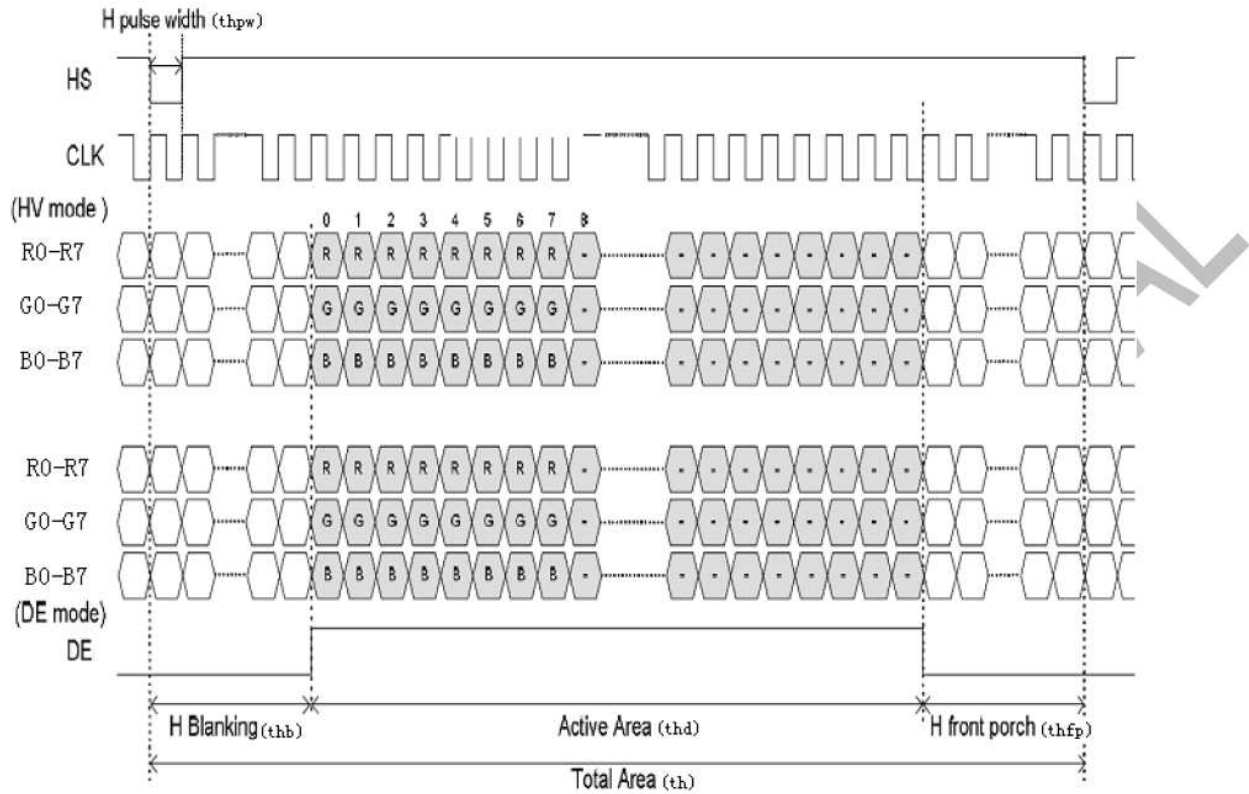
VCC=3.3V, GND=0V, Ta=25°C

Parameter	Symbol	Min	Typ	Max	Unit	Remark
DCLK	F _{clk}	28	30	40	MHZ	
	t _{clk}	20	33.3	36	ns	
HSD	t _h	862	1056	1200	t _{clk}	
	t _{hd}	800	800	800	t _{clk}	
	t _{hpw}	1	-	40	t _{clk}	
	t _{hb}	46	46	46	t _{clk}	
	t _{hfp}	16	210	354	t _{clk}	
VSD	t _v	510	525	650	th	
	t _{vd}	480	480	480	th	
	t _{vpw}	1	3	20	th	
	t _{vb}	23	23	23	th	
	t _{vfp}	7	22	147	th	

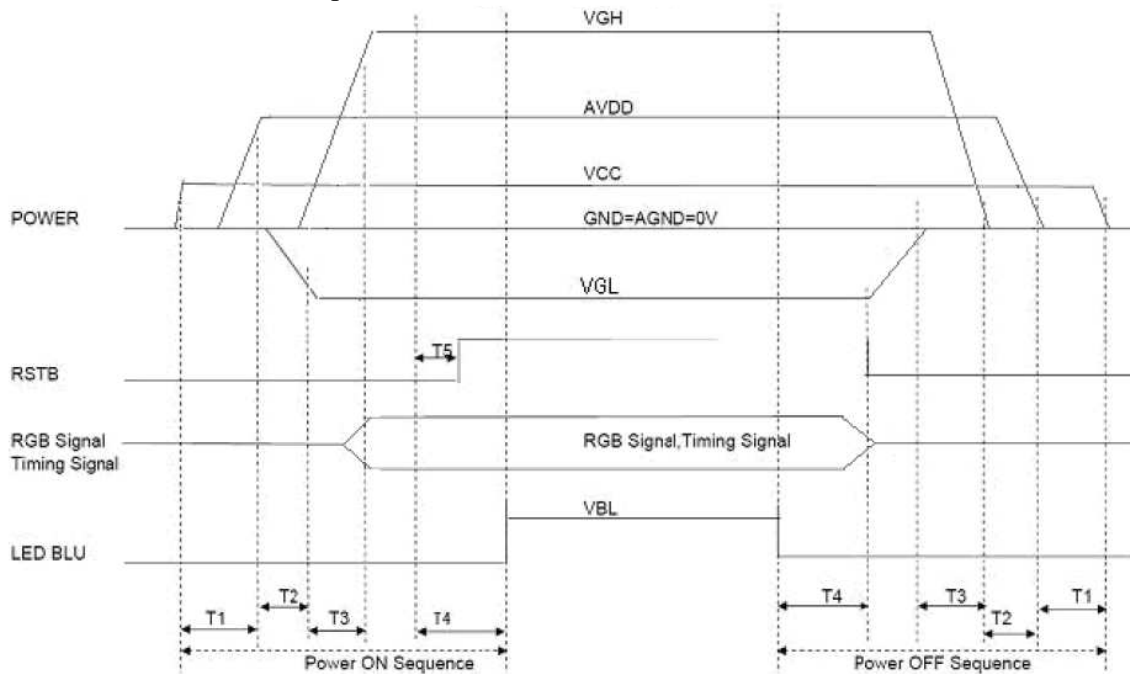
Note 1: DE timing refer to HS, VS input timing.

TCON Vertical Input Timing Diagram HV


TCON Horizontal Input Timing Diagram



1.3 Power ON/OFF Sequence



Note 1: $T1 \geq 20ms$, $T2 \geq 20ms$, $T3 \geq 5ms$, $T4 \geq 100ms$, $T5 \geq 5ms$.

■ RELIABILITY TEST

No.	Test Item	Test Condition	Remark
1	High Temperature Storage	$80 \pm 2^{\circ}\text{C}/240$ hours	IEC60068-2-1 GB2423.2
2	Low Temperature Storage	$-30 \pm 2^{\circ}\text{C}/240$ hours	IEC60068-2-1 GB2423.1
3	High Temperature Operating	$70 \pm 2^{\circ}\text{C}/240$ hours	Note 1,IEC60068-2-1 GB2423.2
4	Low Temperature Operating	$-20 \pm 2^{\circ}\text{C}/240$ hours	IEC60068-2-1 GB2423.1
5	Temperature Cycle storage	$-30 \pm 2^{\circ}\text{C} \sim 25 \sim 80 \pm 2^{\circ}\text{C} \times 100$ cycles (30min.) (5min.) (30min.)	Start with cold temperature, with high temperature, IEC60068-2-14 GB2423.22
6	Damp proof Test operating	$65^{\circ}\text{C} \pm 5^{\circ}\text{C} \times 90\%\text{RH}/240$ hours	Note 2,IEC60068-2-78 GB/T2423.3
7	Vibration Test (non-operation)	Frequency range:10Hz~55Hz, Stroke:1.5mm Sweep:10Hz~55Hz~10Hz 2hours for each direction of X,Y,Z(6 hours for total)	IEC60068-2-6 GB/T2423.10
8	Package drop test	Height:60cm,1 corner,3 edges,6 surfaces	IEC60068-2-32,GB2423.8
9	ESD test (operation)	C=150pF,R=330Ω ,5points/panel Air: ±8KV,5times Contact: ±4KV,5times(Environment: 15°C~35°C,30%~60%,86Kpa~106Kpa)	IEC61000-4-2 GB/T17626.2
10	Shock(non-operation)	100G 6ms, ±X, ±Y, ±Z 3times each direction	IEC60068-2-27 GB/T2423.5

Note 1:Ts is the temperature of panel's surface.

Note 2:Ta is the ambient temperature of sample.

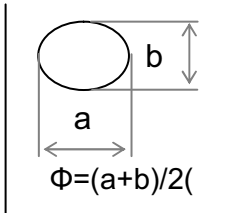
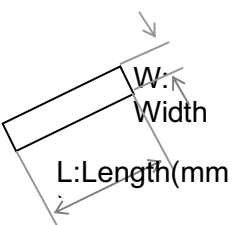
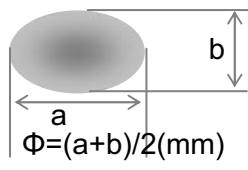
■ INSPECTION CRITERION

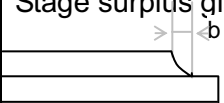
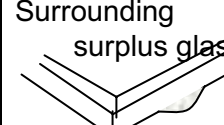
1. Outgoing Inspection Level

Outgoing Inspection standard	Inspection conditions	Inspection				
		Min.	Max.	Unit	IL	AQL
Major Defects	See 9.3 general notes	See 9.5			II	0.65
Minor Defects	See 9.3 general notes	See 9.5			II	1.5

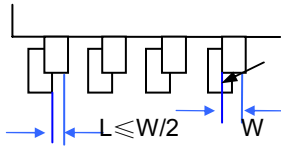
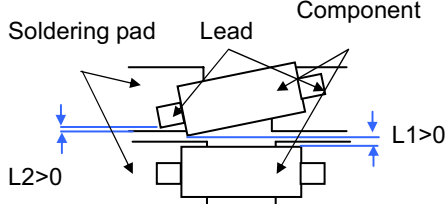
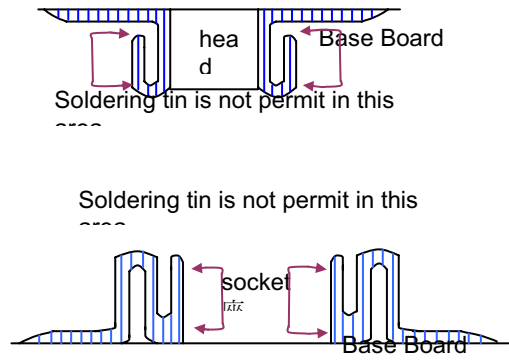
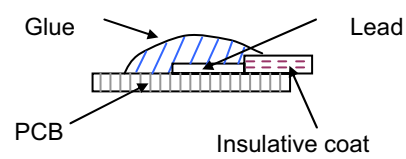
Note : Sampling standard conforms to GB2828

2. Inspection Items And Criteria

Inspection items			Judgment standard					
			Category		Acceptable number			
					A zone	B zone		
1	Black spot, White spot, Bright Spot, Pinhole, Foreign Particle, Particle in or on glass, Scratch on glass		A	$\Phi \leq 0.10$	Neglected			
			B	$0.10 < \Phi \leq 0.15$	2			
			C	$0.15 < \Phi \leq 0.20$	1			
			D	$0.20 < \Phi$	0			
			Total defective point(B,C)		3		Neglected	
2	Black line, White line, and Particle Between Polarizer and glass, Scratch on glass		A	$W \leq 0.01$	Neglected			
			B	$0.01 < W \leq 0.03$ $L \leq 3.0$	2			
			C	$0.03 < W \leq 0.05$ $L \leq 3.0$	1			
			D	$0.05 < W$	0			
			Total defective point(B,C)		3		Neglected	
3	Contrast variation		A	$\Phi \leq 0.2$	Neglected			
			B	$0.2 < \Phi \leq 0.3$	2			
			C	$0.3 < \Phi \leq 0.4$	1			
			D	$0.4 < \Phi$	0			
			Total defective point(B,C)		3		Neglected	
4	Dot defect (if TFT LCD is smaller than 3 inches)		LCD Class	Defect	A area	B area		
			A	Bright dot	1	Neglected		

	used)			Dark dot	2		d		
				Total	2				
				B	Bright dot	2			
				Dark dot	3				
						Total	4		
		TFT LCD between 3~10.4 inches	LCD Class	A	Defect	A area	B area	Neglected	
					Bright dot	1	1		
				B	Dark dot	1	2		
					Total	4			
				A	Bright dot	2	2		
Dark dot	2				3				
	Total	6							
Notes: Bright dot: in R · G · B or dark display figure, the pixel appears bright. Dark dot: in R · G · B or white display figure, the pixel appears dark. Defect area must be less than an half size of the dot.									
5	Bubble inside cell	any size		none		none			
6	Polarizer defect (if Polarizer is used)	Scratch ,damage on polarizer, Particle on polarizer or between polarizer and glass.		Refer to item 1 and item 2.					
		Bubble, dent and convex	A	$\Phi \leq 0.3$	Neglected		Neglected		
			B	$0.3 < \Phi \leq 0.7$	2				
			C	$0.7 < \Phi$	0				
7	Surplus glass	Stage surplus glass 		$b \leq 0.3\text{mm}$					
		Surrounding surplus glass 		Should not influence outline dimension and assembling.					
8	Open segment or open common	Not permitted							
9	Short circuit	Not permitted							
10	False viewing direction	Not permitted							
11	Contrast ratio uneven	According to the limit specimen							
12	Crosstalk	According to the limit specimen							
13	Black /White spot(display)	Refer to item 1							
14	Black /White line(display)	Refer to item 2							

Inspection items		Judgment standard		Acceptable number	
		Category(application: B zone)			
15	Glass defect crack	①The front of lead terminals		A $a \leq t, b \leq 1/5W, c \leq 3\text{mm}$	Max.3 defects allowed
		B Crack at two sides of lead terminals should not cover patterns and alignment mark			
		②Surrounding crack—non-contact side		$b < \text{Inner border line of the seal}$	
		③ Surrounding crack— contact side		$b < \text{Outer border line of the seal}$	
		④Corner		A $a \leq t, b \leq 3.0, c \leq 3.0$	
			B Glass crack should not cover patterns u and alignment mark and patterns.		

Inspection items		Judgment standard	
		Category(application: B zone)	
16	PCB defect	Component soldering: No cold soldering、short、open circuit、burr、tin ball The flat encapsulation component position deviation must be less than 1/3 width of the pin (Pic.1) ; the sheet component deviation: Pin deviates from the pad and contact with the near components is not permitted (Pic.2)	Component  Component Soldering pad Lead Component 
		lead defect: The lead lack must be less than 1/3 of its width; The lead burr must be less than 1/3 of the seam; Impurities connect with the near leads is not permitted	
		Connector soldering: Soldering tin is at contact position of the plug and socket is not permitted No foundation is scald Serious cave distortion on plug and socket contact pin is not permitted	
		Glue on root of the speaker receiver and motor lead: The insulative coat of the lead must join into the PCB; the protected glue must envelop to the insulative coat.	

■ PRECAUTIONS FOR USING LCD MODULES

1 Handling Precautions

- 1.1 The display panel is made of glass and polarizer. As glass is fragile. It tends to become or chipped during handling especially on the edges. Please avoid dropping or jarring. Do not subject it to a mechanical shock by dropping it or impact.
- 1.2 If the display panel is damaged and the liquid crystal substance leaks out, be sure not to get any in your mouth. If the substance contacts your skin or clothes, wash it off using soap and water.
- 1.3 Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary. Do not touch the display with bare hands. This will stain the display area and degraded insulation between terminals (some cosmetics are determined to the polarizer).
- 1.4 The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully. Do not touch, push or rub the exposed polarizers with anything harder than an HB pencil lead (glass, tweezers, etc.). Do not put or attach anything on the display area to avoid leaving marks on it. Condensation on the surface and contact with terminals due to cold will damage, stain or dirty the polarizer. After products are tested at low temperature they must be warmed up in a container before coming in to contact with room temperature air.
- 1.5 If the display surface becomes contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If it is heavily contaminated, moisten cloth with one of the following solvents
 - Isopropyl alcohol
 - Ethyl alcoholDo not scrub hard to avoid damaging the display surface.
- 1.6 Solvents other than those above-mentioned may damage the polarizer. Especially, do not use the following.
 - Water
 - Ketone
 - Aromatic solventsWipe off saliva or water drops immediately, contact with water over a long period of time may cause deformation or color fading. Avoid contact with oil and fats.
- 1.7 Exercise care to minimize corrosion of the electrode. Corrosion of the electrodes is accelerated by water droplets moisture condensation or a current flow in a high-humidity environment
- 1.8 Install the LCD Module by using the mounting holes. When mounting the LCD module make sure it is free of twisting, warping and distortion. In particular, do not forcibly pull or bend the I/O cable or the backlight cable.
- 1.9 Do not attempt to disassemble or process the LCD module.
- 1.10 NC terminal should be open. Do not connect anything.
- 1.11 If the logic circuit power is off, do not apply the input signals.
- 1.12 Electro-Static Discharge Control, Since this module uses a CMOS LSI, the same careful attention should be paid to electrostatic discharge as for an ordinary CMOS IC. To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.
 - Before removing LCM from its packing case or incorporating it into a set, be sure the module and your body have the same electric potential. Be sure to ground the body when handling the LCD modules.

- Tools required for assembling, such as soldering irons, must be properly grounded. Make certain the AC power source for the soldering iron does not leak. When using an electric screwdriver to attach LCM, the screwdriver should be of ground potentiality to minimize as much as possible any transmission of electromagnetic waves produced sparks coming from the commutator of the motor.

- To reduce the amount of static electricity generated, do not conduct assembling and other work under dry conditions. To reduce the generation of static electricity be careful that the air in the work is not too dry. A relative humidity of 50%-60% is recommended. As far as possible make the electric potential of your work clothes and that of the work bench the ground potential.

The LCD module is coated with a film to protect the display surface. Exercise care when peeling off this protective film since static electricity may be generated.

1.13 Since LCM has been assembled and adjusted with a high degree of precision, avoid applying excessive shocks to the module or making any alterations or modifications to it.

- Do not alter modify or change the shape of the tab on the metal frame.
- Do not make extra holes on the printed circuit board, modify its shape or change the positions of components to be attached.
- Do not damage or modify the pattern writing on the printed circuit board.
- Absolutely do not modify the zebra rubber strip (conductive rubber) or heat seal connector.
- Except for soldering the interface, do not make any alterations or modifications with a soldering iron.
- Do not drop, bend or twist the LCM.

2 Handling precaution for LCM

2.1 LCM is easy to be damaged. Please note below and be careful for handling.

2.2 Correct handling:

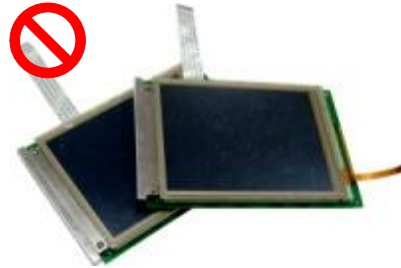


As above picture, please handle with anti-static gloves around LCM edges.

2.3 Incorrect handling:



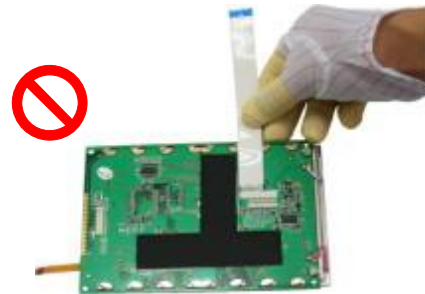
Please don't touch IC directly.



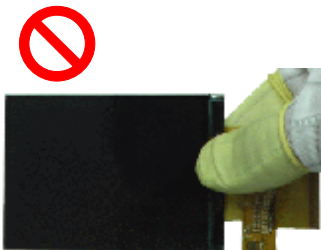
Please don't stack LCM.



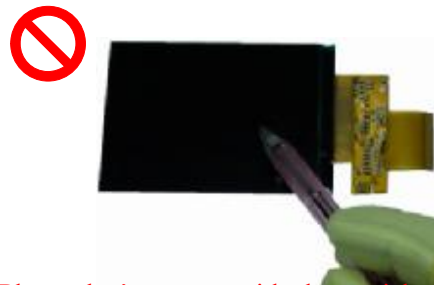
Please don't hold the surface of panel.



Please don't stretch interface of output, such as FPC cable.



Please don't hold the surface of IC.



Please don't operate with sharp stick such as pens.

3 Storage Precautions

3.1 When storing the LCD modules, the following precaution are necessary.

3.1.1 Store them in a sealed polyethylene bag. If properly sealed, there is no need for the desiccant.

3.1.2 Store them in a dark place. Do not expose to sunlight or fluorescent light, keep the temperature between 0°C and 35°C, and keep the relative humidity between 40%RH and 60%RH.

3.1.3 The polarizer surface should not come in contact with any other objects (We advise you to store them in the anti-static electricity container in which they were shipped).

3.2 Transportation Precautions

3.2.1 During shipment, please handle with care. The packaging bag can not be broken, step on trap. Packaging Carton layer height can not be over two meters.

3.2.2 The transportation process should pay attention to the waterproof and moisture-proof measures. Product can not be watering. Ethylene sealed bags can not be unsealed.

3.3 Others

3.3.1 Liquid crystals solidify under low temperature (below the storage temperature range) leading to defective orientation or the generation of air bubbles (black or white). Air bubbles may also be generated if the module is subject to a low temperature.

3.3.2 If the LCD modules have been operating for a long time showing the same display patterns, the display patterns may remain on the screen as ghost images and a slight contrast irregularity may also appear. A normal operating status can be regained by suspending use for some time. It should be noted that this phenomenon does not adversely affect performance reliability.

3.3.3 To minimize the performance degradation of the LCD modules resulting from destruction caused by static electricity etc., exercise care to avoid holding the following sections when handling the modules.

3.3.3.1 - Exposed area of the printed circuit board.

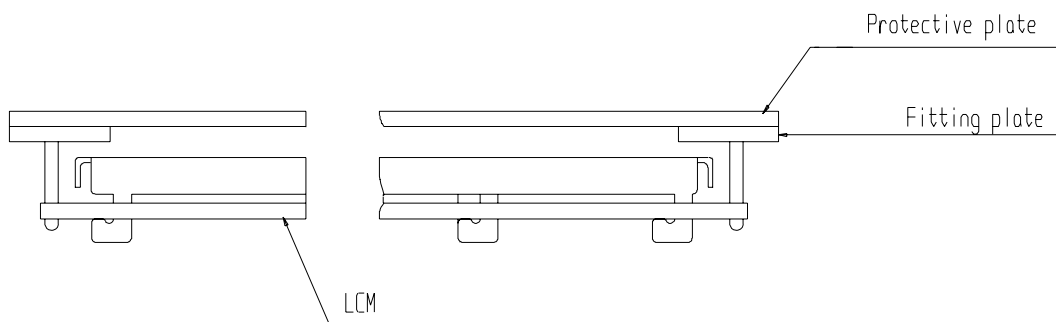
3.3.3.2 -Terminal electrode sections.

4 USING LCD MODULES

4.1 Installing LCD Modules

The hole in the printed circuit board is used to fix LCM as shown in the picture below. Attend to the following items when installing the LCM.

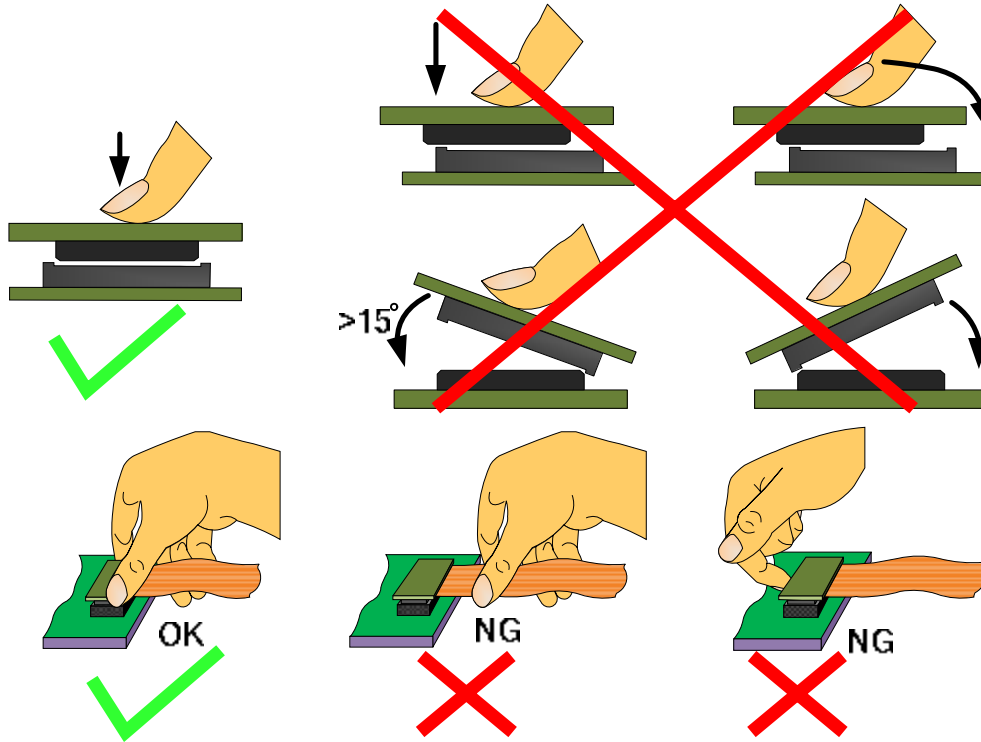
4.1.1 Cover the surface with a transparent protective plate to protect the polarizer and LC cell.



4.1.2 When assembling the LCM into other equipment, the spacer to the bit between the LCM and the fitting plate should have enough height to avoid causing stress to the module surface, refer to the individual specifications for measurements. The measurement tolerance should be $\pm 0.1\text{mm}$

4.2 Precaution for assemble the module with BTB connector:

Please note the position of the male and female connector position, don't assemble or assemble like the method which the following picture shows



4.3 Precaution for soldering the LCM

	Manual soldering	Machine drag soldering	Machine press soldering
No RoHS Product	290°C ~350°C. Time : 3-5S.	330°C ~350°C. Speed : 4-8 mm/s.	300°C ~330°C. Time : 3-6S. Press: 0.8~1.2Mpa
RoHS Product	340°C ~370°C. Time : 3-5S.	350°C ~370°C. Time : 4-8 mm/s.	330°C ~360°C. Time : 3-6S. Press: 0.8~1.2Mpa

4.3.1 If soldering flux is used, be sure to remove any remaining flux after finishing to soldering operation (This does not apply in the case of a non-halogen type of flux). It is recommended that you protect the LCD surface with a cover during soldering to prevent any damage due to flux spatters

4.3.2 When soldering the electroluminescent panel and PC board, the panel and board should not be detached more than three times. This maximum number is determined by the temperature and time conditions mentioned above, though there may be some variance depending on the temperature of the soldering iron.

4.3.3 When remove the electroluminescent panel from the PC board, be sure the solder has completely melted, the soldered pad on the PC board could be damaged.

4.4 Precautions for Operation

4.4.1 Viewing angle varies with the change of liquid crystal driving voltage (VLCD). Adjust VLCD to show the best contrast.

4.4.2 It is an indispensable condition to drive LCDs within the specified voltage limit since the higher voltage than the limit cause the shorter LCD life. An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided

4.4.3 Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, which will come back in the specified operating temperature.

4.4.4 If the display area is pushed hard during operation, the display will become abnormal. However, it will return to normal if it is turned off and then back on.

4.4.5 A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit. Usage under the maximum operating temperature, 50%RH or less is required

4.4.6 Input logic voltage before apply analog high voltage such as LCD driving voltage when power on. Remove analog high voltage before logic voltage when power off the module. Input each signal after the positive/negative voltage becomes stable.

4.4.7 Please keep the temperature within the specified range for use and storage. Polarization degradation, bubble generation or polarizer peel-off may occur with high temperature and high humidity

4.5 Safety

4.5.1 It is recommended to crush damaged or unnecessary LCDs into pieces and wash them off with solvents such as acetone and ethanol which should later be burned

4.5.2 If any liquid leaks out of a damaged glass cell and comes in contact with the hands, wash off thoroughly with soap and water

4.6 Limited Warranty

Unless agreed between Multi-Inno and the customer Multi-Inno will replace or repair any of its LCD modules which are found to be functionally defective when inspected in accordance with Multi-Inno LCD acceptance standards (copies available upon request) for a period of one year from date of production. Cosmetic/visual defects must be returned to Multi-Inno within 90 days of shipment. Confirmation of such date shall be based on data code on product. The warranty liability of Multi-Inno limited to repair and/or replace on the terms set forth above. Multi-Inno will not be responsible for any subsequent or consequential events.

4.7 Return LCM under warranty

4.7.1 No warranty can be granted if the precautions stated above have been disregarded. The typical examples of violations are :

4.7.1.1 - Broken LCD glass.

4.7.1.2 - PCB eyelet is damaged or modified.

4.7.1.3 -PCB conductors damaged.

4.7.1.4 - Circuit modified in any way, including addition of components.

4.7.1.5 - PCB tampered with by grinding, engraving or painting varnish.

4.7.1.6 - Soldering to or modifying the bezel in any manner.

4.7.2 Module repairs will be invoiced to the customer upon mutual agreement. Modules must be returned with sufficient description of the failures or defects. Any connectors or cable installed by the customer must be removed completely without damaging the PCB eyelet, conductors and terminals.

PACKING SPECIFICATION

Please consult our technical department for detail information.

PRIOR CONSULT MATTER

- 1 For Multi-Inno standard products, we keep the right to change material, process ... for improving the product property without prior notice to our customer.
- 2 For OEM products, if any changes are needed which may affect the product property, we will consult with our customer in advance.
- 3 If you have special requirement about reliability condition, please let us know before you start the test on our samples.